



## Lead Free Solder Paste Series for High Performance SMT Applications

Superior solder paste family, especially developed for demanding wide SMT process window application

Microbond® SMT701 and Microbond® SMT712 No Clean Solder Pastes Series is a state of the art lead free solder paste formulation that promotes outstanding printing performance.

For demanding complicated electronics applications such as for smartphones or hybrid electronics, the Halogen Zero formulation of the flux is active enough to provide excellent wetting results under Air atmosphere.

# Microbond® SMT701 and Microbond® SMT712

## For SMT Applications

### Key Features

- Excellent wetting under air
- Low voiding
- High volume print capability
- Anti-solder bead
- Transparent residue
- Improves head on pillow issue

### Standard Product Specification

FC701 Solder Paste	FC712 Solder Paste
No Clean classification	No Clean classification
Halogen Zero	Halogen Zero
Solder Powder Type 4	Solder Powder Type 4 & 5
ROLO	ROLO
SAC305 & SAC105 Alloy	SAC305 Alloy

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